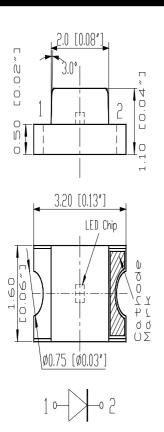
表面黏著型發光二極體指示燈

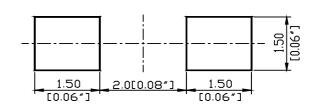
S150 Series SMD Chip LED Lamps

Part Number: Q1500VS4

Package outlines









ITEM	MATERIALS
Resin (mold)	Ероху
Bonding Wire	Ø 25 μ m Au
Lens color	Water transparent
Printed circuit board	BT (white)
Dice	AlGaInP
Emitted color	Red

NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ± 0.1 mm (0.004inch) unless otherwise noted.

表面黏著型發光二極體指示燈

Forward voltage

Luminous intensity

Part Number: Q1500VS4						
Absolute maximum rating	S		(T	A=25	°C)	
Parameter	Syml	ool	Value			Unit
Forward current	If			30		mA
Reverse voltage	Vr			5		V
Power dissipation	Pd			81		mW
Operating temperature range	Тор)	-20 ~+80		$^{\circ}\! \mathbb{C}$	
Storage temperature range	Tst	2	-20 ~+80		$^{\circ}$ C	
Peak pulsing current (1/8 duty	lfp		125		mA	
f=1kHz)	• • • • •		/T 25%			
Electro-optical character			(T _A =25°C)			
Parameter	Test	Symbo	Value		Unit	
	Conditio	l	Min	Тур	Max	
	n					
Wavelength at peak emission	If=20mA	λpeak	630	635	640	nm
Spectral half bandwidth	If=20mA	Δλ		20		nm
Dominant wavelength	If=20mA	λdom	619	624	629	nm

If=20mA

If=20mA

*1

Vf

Ιv

2.20

600

2.70

mcd

Viewing angle at 50% Iv	lf=10mA	201/2	 140		Deg
Reverse current	Vr=5V	lr	 :	10	μΑ

*1 Note: Luminous intensity tolerances are $\pm 10^{\circ}$.

URFACE MOUNT LED LAMPS

表面黏著型發光二極體指示燈

Part Number: Q1500VS4

OPTICAL CHARACTERISTIC CURVES Relative Intensity vs. Wavelength Relative Intensity (%) 100 80 60 40 20 300 400 500 600 700 900 1000 1100 Wavelength (nm) Forward Current vs. Forward Voltage (V) 2,650 2,500 Forward Voltage (V) 2,000 1.500 1,000 0.500 0.000 Forward Current (mA) **Directive Characteristics** 0* -30 30° -60° 60°

0

50%

100%

SURFACE MOUNT LED LAMPS

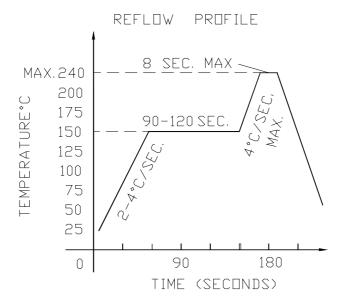
100%

50%

表面黏著型發光二極體指示燈

Reflow Profile

■ Reflow Temp/Time

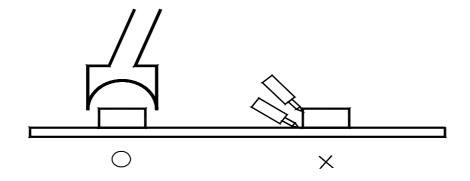


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter

(+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 15W, and temperatures should be controllable .Surface temperature of the device \blacksquare Rework

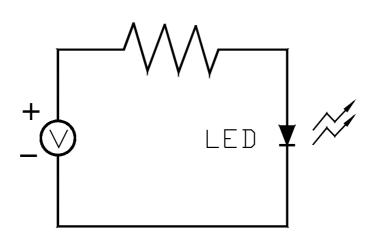
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



表面黏著型發光二極體指示燈

Test circuit and handling precautions

■ Test circuit



Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause

big current change (Burn out will happen).

2.Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5° C~ 30° C(41° F~ 86°)

2.2 Shelf life in sealed bag: 12 month at $<5^{\circ}\text{C}\text{--}30^{\circ}\text{C}$ and <30% R.H. after the package is

Opened, the products should be used within a week or they should be keeping to stored at

 \leq 20 R.H. with zip-lock sealed.

3.Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The

Conditions are as followings:

- 3.1 60 ± 3 °C x(12~24hrs) and <5%RH, taped reel type
- 3.2 $100\pm3^{\circ}$ C x(45min~1hr), bulk type
- 3.3 $130\pm3^{\circ}$ C x(15~30min), bulk type

When you discover that the desiccant in the package has a pink color (normal=blue), you

Should treat them in the same conditions as (3.1-3.3)

表面黏著型發光二極體指示燈

Test items and results of reliability						
Туре	Test Item	Test Conditions	Note	Number of Damaged		
Eaquement →	Temperature Cycle	-20°C 30min ↑↓ 80°C 30min	100 cycle	0/22		
	Thermal Shock	-20°C 15min ↑↓ 80°C 15min	100 cycle	0/22		
	High Humidity Heat Cycle	30°C⇔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22		
	High Temperature Storage	T _a =80°C	1000 hrs	0/22		
	Humidity Heat Storage	T _a =60°C RH=90%	1000 hrs	0/22		
ajon	Low Temperature Storage	T _a =-30°C	1000 hrs	0/22		
Se Opena tion	Life Test	T _a =25°C I _F =20mA	1000 hrs	0/22		
	High Humidity Heat Life Test	60°C RH=90% I _F =20mA	500 hrs	0/22		
	Low Temperature Life Test	T _a =-20°C I _F =20mA	1000 hrs	0/22		